

CLAIM CHANGES:

1. (Original) A component mounting circuit board comprising:  
a circuit pattern including a plurality of electrically conductive plates;  
an inner electrical component electrically connected to the circuit pattern;  
and a resin molded section made of a resin by way of molding so as to cover the  
circuit pattern and the inner electrical component, the resin molded section having an opening  
allowing an outer electrical component located outside the resin molded section to be  
connected to the circuit pattern therethrough.
2. (Original) The component mounting circuit board according to claim 1, wherein  
the resin molded section is made of an epoxy resin.
3. (Previously Amended) The component mounting circuit board according to claim  
1, wherein a portion of the circuit pattern corresponding to the inner electrical component has  
member coupled thereto, the member and the portion being thicker than the remaining circuit  
pattern.
4. (Previously Amended) The component mounting circuit board according to claim  
1, wherein the circuit pattern corresponding to the inner electrical component has an exposed  
portion exposed to the outside the resin molded section.
5. (Original) The component mounting circuit board according to claim 1, further  
comprising a metal member embedded in the resin molded 1, further comprising a metal

member embedded in the resin molded section so as to be located to correspond to a portion of the inner electrical component and electrically insulated from the circuit pattern, the metal member being provided with an exposed portion exposed outside the resin molded section.

6. (Original) The component mounting circuit board according to claim 1, further comprising a metal member embedded in the resin molded section so as to be located at a portion corresponding to the inner electrical component, the metal member being discrete from the circuit pattern.

7. (Original) The component mounting circuit board according to claim 1, further comprising a support provided on the resin molded section to support the outer electrical component.

8. (Original) The component mounting circuit board according to claim 1, further comprising a terminal provided on the circuit pattern so as to project outside the resin molded section.

9. (Original) The component mounting circuit board according to claim 1, wherein the inner electrical component is connected to the circuit pattern by wire bonding.

10. (Original) The component mounting circuit board according to claim 1, wherein the outer electrical component is soldered to a portion of the circuit pattern corresponding to the opening.

11. (Previously Amended) A microwave oven comprising:  
a magnetron; and  
a component mounting circuit board including, at least, a power supply circuit for driving the magnetron, and a switching circuit mounted thereon,  
the component mounting circuit board includes a circuit pattern including a plurality of electrically conductive plates;  
an inner electrical component electrically connected to the circuit pattern; and  
a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component.

12. (Original) The component mounting circuit board according to claim 11, wherein the resin molded section includes an opening used when an outer electrical component located outside the resin molded section is connected to the circuit pattern.

13. (Original) A method of making a component mounting circuit board comprising the steps of:  
electrically connecting an inner electrical component to a circuit pattern including a plurality of electrically conductive plates;  
covering the circuit pattern and the inner electrical component with a resin, thereby forming a resin molded section having an opening; and  
electrically connecting an outer electrical component located outside the resin molded section through the opening.